

# MA2YD26

## Silicon epitaxial planar type

For high speed switching

### ■ Features

- Forward current (Average)  $I_{F(AV)} = 800$  mA rectification is possible
- Reverse voltage  $V_R = 60$  V is guaranteed
- Small reverse current  $I_R$
- Mini type 2-pin package

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	60	V
Maximum peak reverse voltage	$V_{RM}$	60	V
Forward current (Average) *1	$I_{F(AV)}$	800	mA
Non-repetitive peak forward surge current *2	$I_{FSM}$	3	A
Junction temperature	$T_j$	125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$

Note) \*1: Mounted on a alumina PC board

\*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

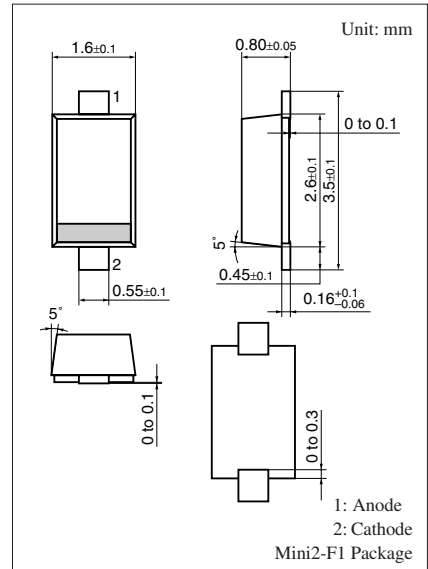
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 800$ mA		0.51	0.58	V
Reverse current	$I_R$	$V_R = 45$ V			100	$\mu\text{A}$
Terminal capacitance	$C_t$	$V_R = 0$ V, $f = 1$ MHz		125		pF
Reverse recovery time *	$t_{rr}$	$I_F = I_R = 100$ mA $I_{tr} = 0.1 \cdot I_R$ , $R_L = 100$ $\Omega$		8		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

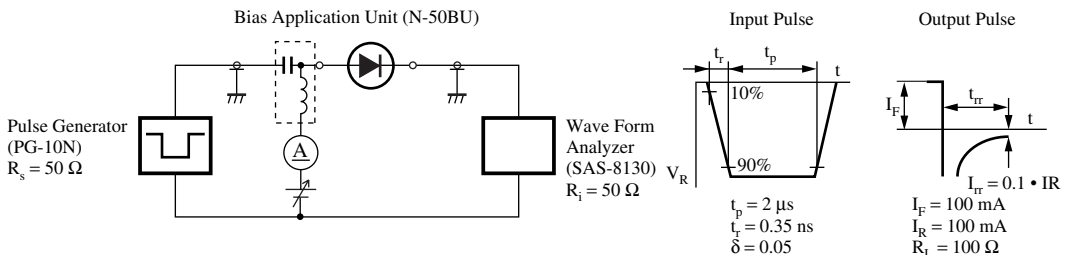
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

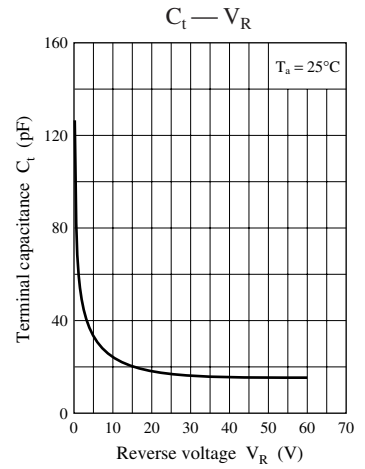
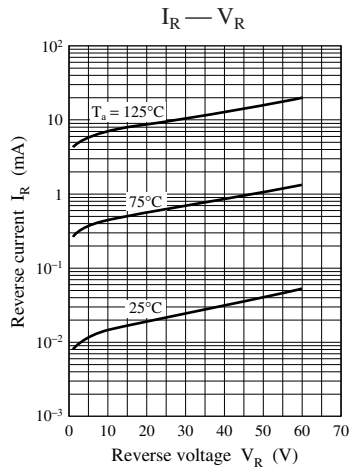
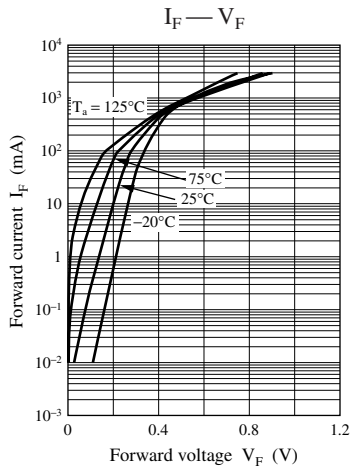
3. Rated input/output frequency: 250 MHz

4. \*:  $t_{rr}$  measuring instrument



Marking Symbol: 2Y





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